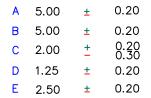
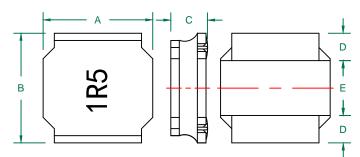
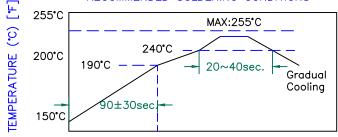
# TYS50201R5N-10

#### PHYSICAL DIMENSIONS:

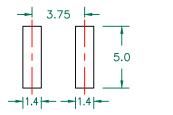


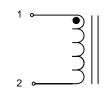


#### RECOMMENDED SOLDERING CONDITIONS



### LAND PATTERNS FOR REFLOW SOLDERING

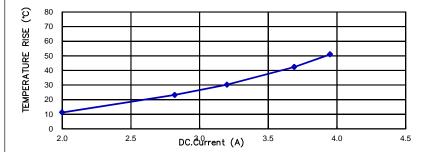




#### **ELECTRICAL SPECIFICATION**

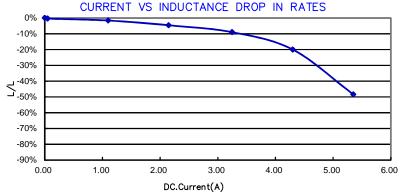
	Min	Nom	Max
INDUCTANCE (uH) L @ 100 KHz/1V ± 30%	1.05	1.50	1.95
DCR (Ω)			0.034

## CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	4.10
SRF (MHz)	68
Temperature Rise Current (A)	3.20



#### NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
  A. AMBIENT TEMPERATURE: 20±15°C.
  B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)

#### 5.TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

	DIMENSIONS ARE IN mm .			This print is the property of Laird Tech. and is loaned in confidence subject to return upon request a with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	nd	Laird			
				PROJECT/PART NUMBER:	REV	PART T		DRAWN BY:	
С	CHANGE DIMENSIONS: C	07/28/16			C		WER ICTOR	QIU	
В	CHANGE LOGO	12/20/12			CALE: N	TS	SHEET:		
Α	ORIGINAL DRAFT	06/06/12	QIU		OOL #	10			
REV	DESCRIPTION	DATE	INT		··· ,			1 of 1	